# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

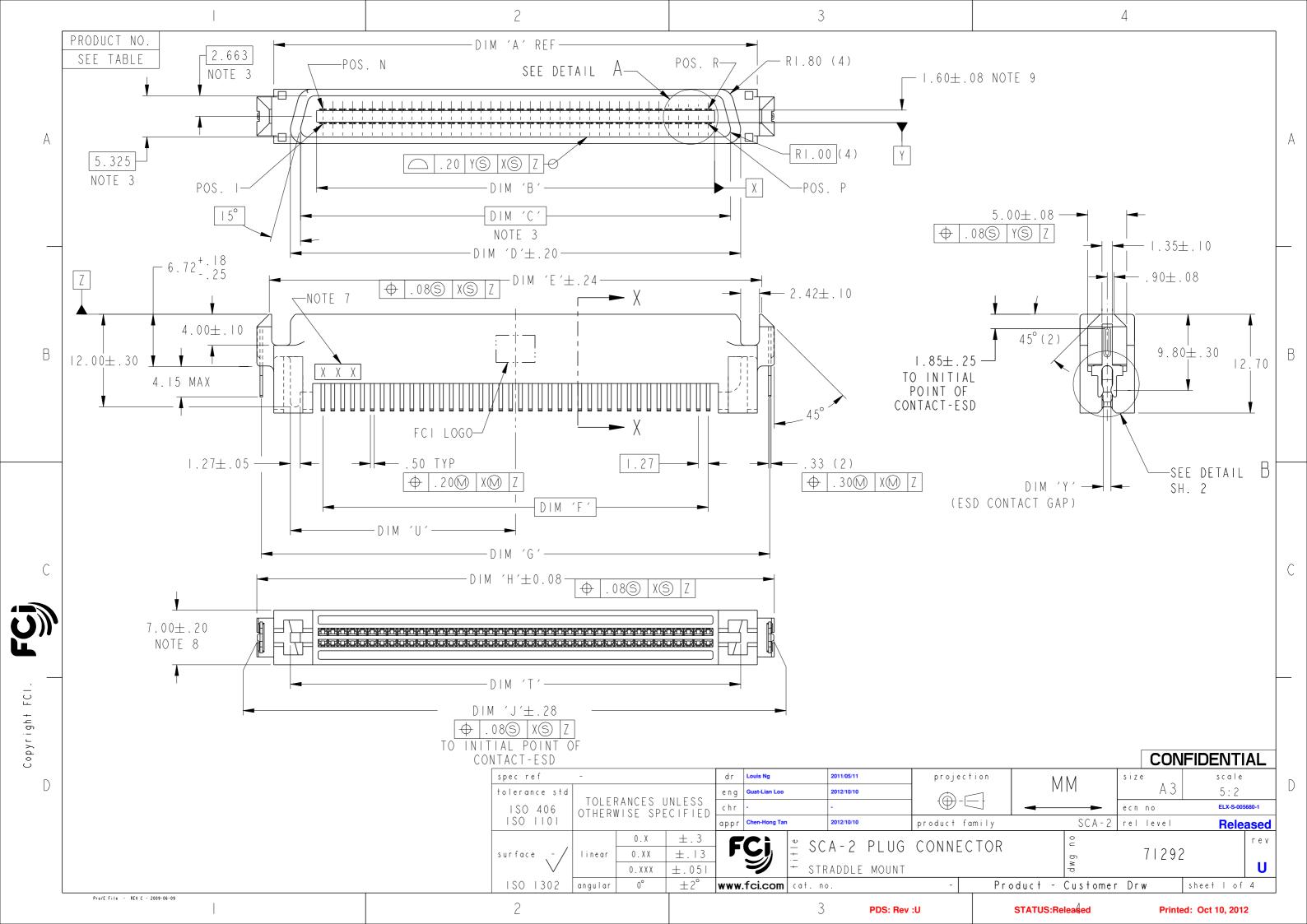
We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

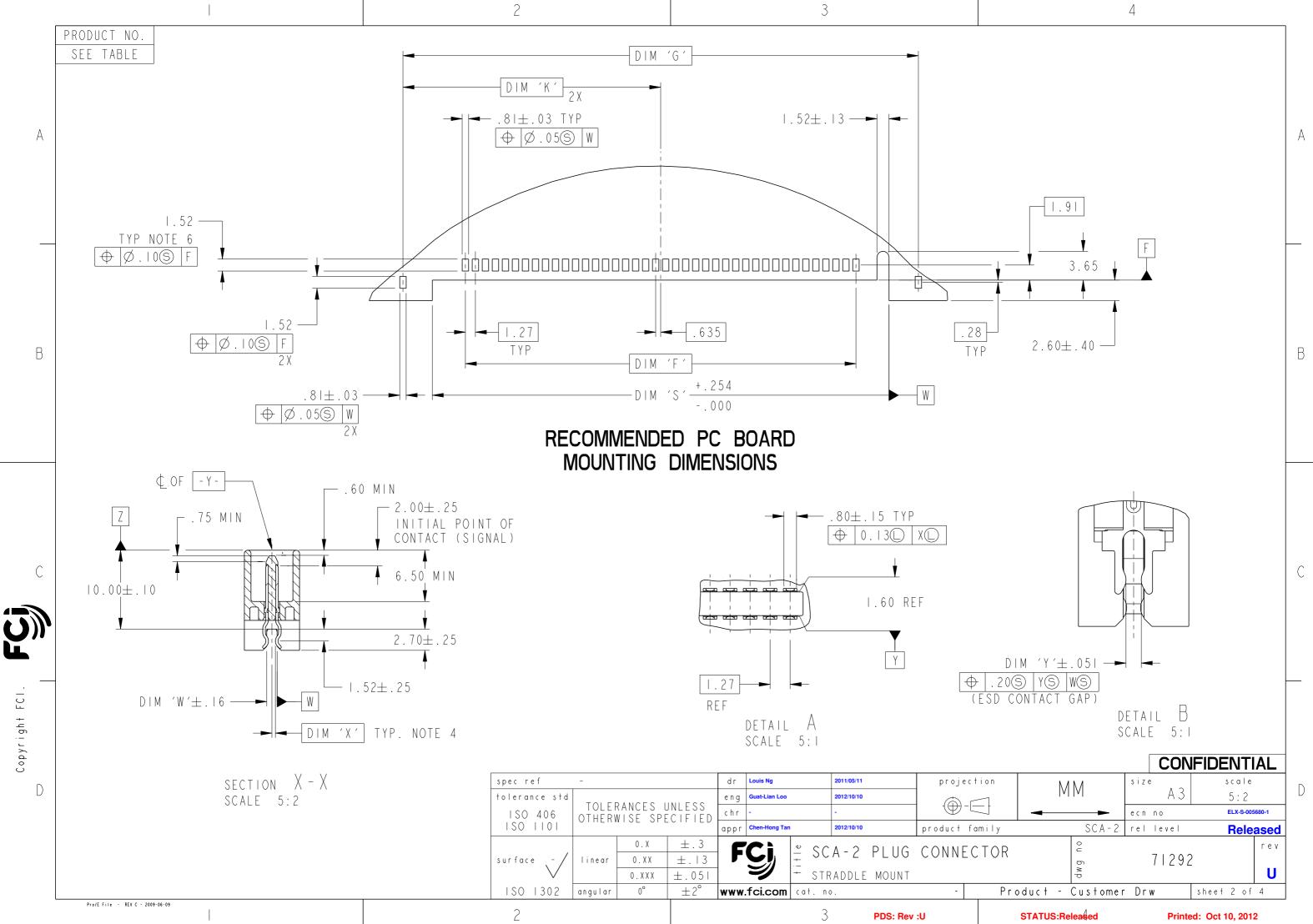


## Contact us

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	PRODUCT NO.	NO. POS.	RECOMMENDED PCB THICKNESS	DIM A REF	DIM B	B DIM C	DIM D	DIM E	DIM F	DIM G	DIM H	DIM .	DIM K	POS N	. POS. P	POS. R	DIM S	DIM T	DIM U	DIM V	DIM W	DIM X	DIM Y	PLATING	
	7   2 9 2 - 0 0																57.91	57.82	28.88	1.32	1.30		0.97	NOTE 2	
	-00 5	80	1.19	62.15	51.17	7 55.27	57.87	63.30	49.53	65.36	66.50	66.40	32.68	4	40	80						0.44			
A	-   0   S																							NOTE IO	
	7 292-002																							NOTE 2	
	-002S	-0025 40	1.19	1.19 36.75 2	25.77	7 29.87	32.47	37.90	24.13	39.95	95 41.10	41.00	19.98	21	20	40	40 32.52	2 32.41	16.20	1.32	1.30	0.44	0.97		
	-   02S																							NOTE IO	
	7 292-003S	80	1.57	62 15	51 17	55.27	57 87	63 30	19 53	65 36	66 50	66 10	32 68		10	80	57 91	57 82	28 88	1 83	1 83	0 72	1 52	NOTE 2	
	-   035	00	1.57	02.15	51.17	55.21	51.01	05.50	49.00	05.50	00.50	00.40	52.00	41	40	00	51.51	51.02	20.00	1.05	1.05	0.12	1.52	NOTE IO	
	7 292-004S	10	1.57	36 75	25 77	29.87	22 17	37 90	21 13	30 05				21	20	10	32 52			1 83	1 83		1 52	NOTE 2	
	-   0 4 S	- 1045	1.51	50.15		23.01	52.41	51.30	L4.1J	59.95	41.10	41.00	19.90			40		52.41	10.20	1.05	1.05	0.12	1.52	NOTE IO	

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#### В NOTES:

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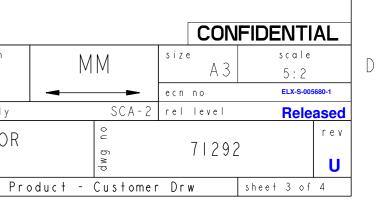
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- I. HOUSING : LCP, UL94V-0 RATED, COLOR: BLACK CONTACTS: PHOSPHOR-BRONZE ESD CONTACT: PHOSPHOR-BRONZE
- 2. PLATING: CONTACTS: 0.76µm (30µ") MIN GXT IN CONTACT AREA, 2.54µm (IOOµ") MIN TIN-LEAD ON P.C. BOARD LEG, 1.27µm (50µ") MIN NICKEL UNDERPLATE OVER ENTIRE TERMINAL. ESD CONTACT: 2.54µm (100µ") MIN TIN-LEAD PLATING W/I.27µm (50µ") NICKEL UNDERPLATE.
- (3) MEASURED AT THE FLOOR OF THE CAVITY MEASURED 6mm FROM DATUM - Z-
- (4) APPLIES TO ALL SURFACES OF CONTACT TAILS.
- (5) MAXIMUM BOARD THICKNESS THAT CONNECTOR CAN ACCOMODATE IS DEFINED BY DIM 'V'.
- (6) THESE DIMENSIONS RESULT IN THE CONTACT RESTING IN CENTER OF PAD WIDTH. THESE DIMENSIONS ARE SUBJECT TO CHANGE DEPENDING ON CUSTOMER'S MANUFACTURING PREFERENCES IN PROCESS SOLDER PLACEMENT AND REFLOW.
- (7) DATE CODE IN THIS AREA.

- (8) MEASUREMENT MADE AT CENTER OF PART, MAY BE AS LOW AS 6.55. DESIGN TO BE MADE TO ACHIEVE THE NOMINAL DIMENSION ACROSS THE ENTIRE PART.
- (9) DISTANCE MEASURED ACROSS CONTACT MATING SURFACES ALONG EFFECTIVE MATING AREA AND CONTACT MUST BE ABOVE PLASTIC ALONG EFFECTIVE MATING AREA.
- IO. PLATING:
  - CONTACTS: 0.76µm (30µ") MIN GOLD IN CONTACT AREA, 2.54µm (IOOµ") MIN TIN-LEAD ON P.C. BOARD LEG, I.27µm (50µ") MIN NICKEL UNDERPLATE OVER ENTIRE TERMINAL. ESD CONTACT: 2.54µm (100µ") MIN TIN-LEAD PLATING W/I.27µm (50µ") NICKEL UNDERPLATE.
- II. PART NUMBERS ENDING IN -Oxx OR -OxxS OR -IxxS ARE MANUFACTURED WITH BRIGHT FINISH TIN-LEAD PLATING IN P.C. BOARD LEG AREA.

spec ref	-			dr	Louis Ng		2011/05/11		proje	ection
tolerance std	T 0 1 5 1			eng	Guat-Lian Loo		2012/10/10			$\square$
ISO 406		RANCES U VISE SPE		chr	-		-			
ISO   0				appr	Chen-Hong Tan		2012/10/10		product	family
		0.X	±.3	ſ		• cC	۸ C	PLUG		
surface -	linear	0.XX	±. 3	▏┍	Ċj	- SC	A - Z	FLUU	CONNE	
		0.XXX	±.051	]	Y	⁺ str	ADDLE	MOUNT		
ISO I302	angular	0°	$\pm 2^{\circ}$	www	fci.com	cat.no	).		-	
2						3			.11	
Ĺ						J		PDS: Rev	:0	

Pro/F File - REV C - 2009-06-09



STATUS:Released

Printed: Oct 10, 2012

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	PRODUCT NO.	NO. POS.	RECOMMENDED PCB THICKNESS	DIM A REF	DIM	B D	IM C	DIM D	DIM E	DIM F	DIM	G D	IM H	DIM J	DIM K	POS. N	. POS. P	POS. R	DIM S	DIM T	DIM (	DIM V	DIM W	DIM X	DIM Y	PLATING		
	71292-001LF	- 80	1.19	62 15	51 17	7 5	55 27	57 87	63 30	10 53	65 3	6 6	66.50	66 10	32 68	11	40	80	57 01	57.82	28 88	1.32	1.30	0 11	4 0.97	NOTE 16		
	- 201 L F	00	1.15	02.15	51.1		J. Z I	51.01	03.30	49.33	05.5		0.50	00.40	52.00	41	40	00	51.51	51.02	20.00	1.52	1.30	0.44	0.31	NOTE 12		
А	71292-002LF	- 40	40	. 9	36.75	25 77	7 20	29 87	32 17	37 90	2/ 13	39 9	5 1		11 00	19.98	21	20	10	32 52	32 /1	16 20		30	0 4 4	0.97	NOTE 16	
	-202LF			1.15		23.1		5.01	52.41	51.50	24,13	55.5	5 4	1,10	41,00			20	40	JL.JL	52.41	10.20	1.52	1.50	0,44	0.51	NOTE 12	
	71292-003LF	F 80	1.57	62 15	51 17	7 5	5 27	57 87	63 30	19 53	65 36	6 6	66.50	66 10	32 68		10	80	57 91	57 82	28 88	5 1.83	1.83	0 72	1.52	NOTE 16		
	- 203LF		1.57	02,10	51,1		J, L I	51.01	00.00	40,00	00.0		0.00	00,40	52.00	41	40		51,51	51.02	20.00	1.00	1.00	0.12	1.52	NOTE 12		
	71292-004LF	40	1.57	36 75	25 7	7 2	9 87	32.47	37 90	21 13	399	5 1		11 00	19 98	21	20	10	32 52	32 /1	16 20	1.83		0 72	1 52	NOTE 16		
	- 204LF		1.07	00.10			5.01	JL, 41	01.00				1,10	+1,00	10.00							1.00		0.12	1.52	NOTE 12		

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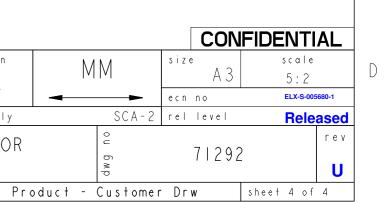
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- 12. PLATING:CONTACT: 0.76μm (30μ") MIN GOLD IN CONTACT AREA, 2.54μm (100μ") - 5.08μm (200μ") TIN (LEAD-FREE) ON P.C. BOARD LEG, 1.27μm (50μ") MIN NICKEL UNDERPLATE OVER ENTIRE TERMINAL. ESD CONTACT: 2.54μm (100μ") - 5.08μm (200μ") TIN PLATING (LEAD-FREE) WITH 1.27μm (50μ") NICKEL UNDERPLATE.
- (3. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR IO SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- (4). THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 15. PART NUMBERS ENDING IN "LF" MEANS FOR NOTE 14 LEAD FREE IDENTIFICATION. P/N XXXXX-2XXLF IS EQUIVALENT TO PREVIOUS P/N XXXXX-2XX.
- 16. PLATING:CONTACT: 0.76μm (30μ") MIN GXT IN CONTACT AREA, 2.54μm (100μ") - 5.08μm (200μ") TIN (LEAD-FREE) ON P.C. BOARD LEG, 1.27μm (50μ") MIN NICKEL UNDERPLATE OVER ENTIRE TERMINAL. ESD CONTACT: 2.54μm (100μ") - 5.08μm (200μ") TIN PLATING (LEAD-FREE) WITH 1.27μm (50μ") NICKEL UNDERPLATE.
- 17. A ZUX SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

spec ref	-			dr	Louis Ng		:	2011/05/11		proj	ec†	ion
tolerance std				eng	Guat-Lian Loo		:			_	-1	
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ISO   0				appr	Chen-Hong Tan	l	:	2012/10/10		product	far	mil
		0.X	±.3	l C		• (		۸_ C		CONN		Т
surface -	linear	0.XX	±. 3		Çj	+	) (, F	4 <sup>-</sup> Z	FLUU	CONN	ECIV	
		0.XXX	±.051	1	Y	+ S	STR/	ADDLE	MOUNT			
ISO I302	angular	0°	±2°	www	fci.com	cat.	no.			-		
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